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TITLE: PBGA, 324 I/O, 23 X 23 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ASS23840W	REV: E	
	CASE NUMBER: 1158-03	25 JAN 2007	
	STANDARD: JEDEC MS-034 AAJ-1		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

6. PACKAGE CODES:

5241: 2 LAYER 324 PBGA

5366: 4 LAYER 324 TEPBGA PGE

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